

SPECIFICATION

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OLED SPECIFICATION

Model No:

REH012864KYPP3N00F00

CUSTOMER:

APPROVED BY								
PCB VERSION								
DATE								
FOR CUSTOMER USE	ONLY							
SALES BY	APPROVED BY	CHECKED BY	PREPARED BY					
APPROVAL FOR SPECIFICATIONS ONLY								

APPROVAL FOR SPECIFICATIONS AND SAMPLE



1. Revision History

VERSION	DATE	REVISED PAGE NO.	Note
0	2017/02/22		First release
А	2018/03/02		Modify Reliability test
			Condition
В	2018/03/30		Modify Contour
			Drawing and Interface
			Pin Function
С	2018/11/27		Modify Static
			electricity test
			Content of Test
D	2019/09/02		Modify Precautions in
			use of OLED Modules



Contents

- **1.General Specification**
- 2. Module Classification Information
- **3.Interface Pin Function**
- 4.Contour Drawing & Block Diagram
- 5. Absolute Maximum Ratings
- **6.**Electrical Characteristics
- 7. Optical Characteristics
- 8.OLED Lifetime
- 9.Reliability
- 10.Inspection specification
- 11.Precautions in use of OLED Modules



1.General Specification

The Features is described as follow:

- Dot Matrix: 128 x 64
- Module dimension: 89.7 × 47.2 x 3.40 mm
- Active Area: 61.41 x 30.69 mm
- Pixel Size: 0.45 x 0.45 mm
- Pixel Pitch: 0.48 x 0.48 mm
- Display Mode: Passive Matrix
- Display Color: Monochrome (Yellow)
- Drive Duty: 1/64 Duty
- IC: SSD1309Z
- Interface: 6800,8080,SPI,I2C
- Size: 2.7 inch



2.Module Classification information

1	2	3	4	5	6	7	8	9	10	11	12	13	14
R	Е	Н	01286	4 K	Y	Р	Р	3	Ν	0	0	F	00
								I		1		Ċ	
1	Brand	d∶Ray	star Opt	ronics Inc).								
2	E : O	LED											
3	Display Type X : COG H						H :		COB Graphic COG + FR TAB				
4	Dot N	latrix ∶	128*64	ŀ									
5	Serie	S											
6	Emitting Color A : Amber B : Blue G : Green S : Sky B				en		R : Red W : White Y : Yellow X : Dual Color			C	Full C	Color	
7	Polar	izer		P∶With A∶Anti-				ut Pola	arizer				
8	Displa	ay Mo	de	P : Pase	sive Ma	atrix ; I	N : Act	ive Ma	ıtrix				
9	Drive	r Voltag	ge	3:3.0~									
10	Touch	n Panel		N : With		ich ba	inel; T:	With to	ouch pa	anel			
11	1 Product type 0 : Standard 1 : Daylight Readable 2 : Transparent OLED (TOLED) 3 : Flexible OLED (FOLED) 4 : OLED Lighting								00				
12	Inspe	ection G	irade	0 : Standard 2 : B grade C : Automotive grade Y : Consumer grade						5			
13	Optio			0 : Defa				I: Hot	bar Fl	PC; D	: Dem	o Kit	
14	Seria	l No.		Serial n	umber(00~ZZ	Z)			10	20	60	is !



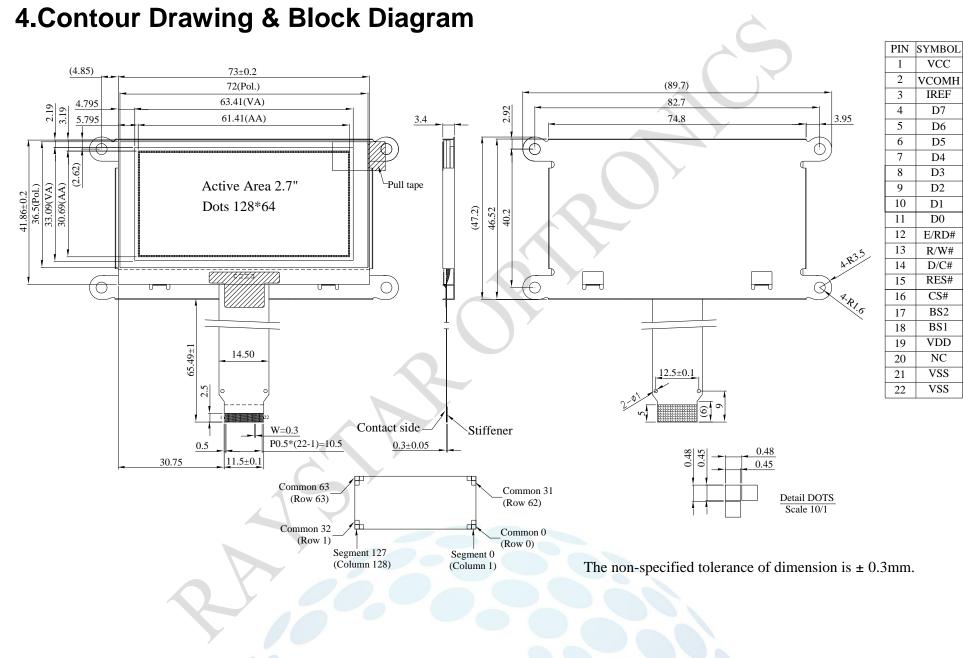
3.Interface Pin Function

No.	Symbol	Function
1	VCC	Power supply for panel driving voltage. This is also the most positive power voltage supply pin.
2	VCOMH	COM signal deselected voltage level. A capacitor should be connected between this pin and VSS.
3	IREF	This pin is the segment output current reference pin. IREF is supplied externally.
4~11	D7~D0	These pins are bi-directional data bus connecting to the MCU data bus. Unused pins are recommended to tie LOW. When serial interface mode is selected, D0 will be the serial clock input: SCLK; D1 will be the serial data input: SDIN and D2 should be kept NC. When I2C mode is selected, D2, D1 should be tied together and serve as SDAout, SDAin in application and D0 is the serial clock input, SCL.
12	E/RD#	This pin is MCU interface input. When 6800 interface mode is selected, this pin will be used as the Enable (E) signal. Read/write operation is initiated when this pin is pulled HIGH and the chip is selected. When 8080 interface mode is selected, this pin receives the Read (RD#) signal. Read operation is initiated when this pin is pulled LOW and the chip is selected. When serial or I2C interface is selected, this pin must be connected to VSS.
13	R/W#	This pin is read / write control input pin connecting to the MCU interface. When 6800 interface mode is selected, this pin will be used as Read/Write (R/W#) selection input. Read mode will be carried out when this pin is pulled HIGH and write mode when LOW. When 8080 interface mode is selected, this pin will be the Write (WR#) input. Data write operation is initiated when this pin is pulled LOW and the chip is selected. When serial or I2C interface is selected, this pin must be connected to VSS.
14	D/C#	This pin is Data/Command control pin connecting to the MCU. When the pin is pulled HIGH, the data at D[7:0] will be interpreted as data. When the pin is pulled LOW, the data at D[7:0] will be transferred to a command register. In I2C mode, this pin acts as SA0 for slave address selection. When 3-wire serial interface is selected, this pin must be connected to VSS.



15	RES#	This pin is reset signal input. When the pin is pulled LOW, initialization of the chip is executed. Keep this pin pull HIGH during normal operation.					
16	CS#	This pin is the chip select input connecting to the MCU. The chip is enabled for MCU communication only when CS# is pulled LOW (active LOW).					
17	BS2	MCU bus interface selection pins. Select appropriate logic setting as					
18	BS1	described in the following table. BS2, BS1 and BS0 are pin select BS1 BS2 I2C 1 0 4-wire Serial 0 0 8-bit 68XX Parallel 0 1 8-bit 80XX Parallel 1 1 Note (1) 0 is connected to VSS (2) 1 is connected to VDD					
19	VDD	Power supply pin for core logic operation					
20	NC	No connection					
21	VSS	Ground.					
22	VSS	Ground.					

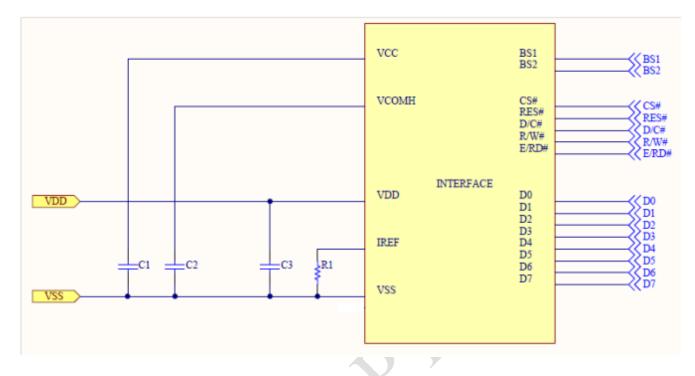




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4.1 Application recommendations



Recommended components: C1, C2 : 2.2uF/25V/0603 C3 : 1.0uF/16V/0603

Bus Interface selection: (Must be set the BS[2:1], refer to item 4) 8-bits 6800 and 8080 parallel, SPI, I2C

Voltage at IREF \approx VCC - 3V. For VCC = 13V, IREF = 10uA: R1 = (Voltage at IREF - VSS) / IREF \approx (13 - 3)V / 10uA = 1M ohm

*For more information, please refer to Application Note provided by Raystar Optronics.





5.Absolute Maximum Ratings

5.Parameter	Symbol	Min	Мах	Unit	Notes
Supply Voltage for Logic	VDD	-0.3	4	V	1, 2
Supply Voltage for Display	VCC	0	15	V	1, 2
Operating Temperature	TOP	-40	+80	°C	
Storage Temperature	TSTG	-40	+85	°C	-

Note 1: All the above voltages are on the basis of "VSS = 0V".

Note 2: When this module is used beyond the above absolute maximum ratings, permanent breakage of the module may occur. Also, for normal operations, it is desirable to use this module under the conditions according to Section 6 "Electrical Characteristics". If this module is used beyond these conditions, malfunctioning of the module can occur and the reliability of the module may deteriorate



6.Electrical Characteristics

6.1 DC Electrical Characteristics

ltem	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage for Logic	VDD		2.8	3.0	3.3	V
Supply Voltage for Display	VCC		12.5	13.0	13.5	V
High Level Input	VIH		0.8×VDD		×	V
Low Level Input	VIL		- (0.2×VDD	V
High Level Output	VOH	_	0.9×VDD			V
Low Level Output	VOL			-	0.1×VDD	V
50% Check Board operating	g Current	VCC =13.0V	- Y	22.0	33.0	mA



6.2 Initial code

}

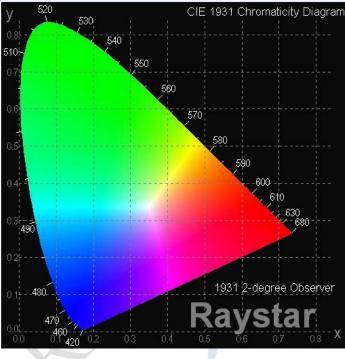
void Initial_SSD1309ZC(){

Write_command(0xAE);	// Display Off
Write_command(0xAD); Write_command(0x8e);	// Master Configuration // Select external VCC supply
Write_command(0xA8); Write_command(0x3F);	// Select Multiplex Ratio // Default => 0x3F (1/64 Duty) 0x1F(1/32 Duty)
Write_command(0xD3); Write_command(0x00);	//Setting Display Offset //00H Reset
Write_command(0x00);	//Set Column Address LSB
Write_command(0x10);	//Set Column Address MSB
Write_command(0x40);	//Set Display Start Line
Write_command(0x00);	<pre>//;Set Memory Addressing Mode Default => 0x02 //0x00 => Horizontal Addressing Mode</pre>
Write_command(0xA6);	//Set Normal Display
Write_command(0xDB); Write_command(0x3c);	//Set Deselect Vcomh level //~0.83xVCC
Write_command(0xA4);	//Entire Display ON
Write_command(0x81); Write_command(0xFF);	//Set Contrast Control for Bank 0
Write_command(0xD5); Write_command(0xF0);	//SET DISPLAY CLOCK //105HZ
Write_command(0xD8); Write_command(0x05);	//Select Area color ON/OFF //MONO Mode and Low Power display Mode
Write_command(0xA1);	//Set Segment Re-Map Default => 0xA0 //0xA1 (0x01) => Column Address 0 Mapped to SEG131
Write_command(0xC8);	//Set COM Output Scan Direction Default => 0xC0
Write_command(0xDA); Write_command(0x12);	<pre>//0xC8 (0x08) => Scan from COM63 to 0 //Set COM Hardware Configuration //Alternative COM Pin</pre>
Write_command(0xD9); Write_command(0xF1); Write_command(0xFF);	//Set Pre-Charge period //Refer to SPEC 34PAGE
Write_command(0xAF);	// Display ON



7.Optical Characteristics

ltem	Symbol	Condition	Min	Тур	Max	Unit
View Angle	(V)θ	—	160		-	deg
view / algie	(Н)ф		160	_	~~~	deg
Contrast Ratio	CR	Dark	2000:1	_	-)	_
Response Time	T rise		-	10		μs
	T fall			10	-	μs
Display with 50% check Board Brightness				80		cd/m2
CIEx(Yellow)	x,y(CIE1931)	0.45	0.47	0.49		
CIEy(Yellow)	x,y(CIE1931)	0.48	0.50	0.52		





8.OLED Lifetime

ITEM	Conditions	Min	Тур	Remark
Operating Life Time	Ta=25°C / Initial 50% check board brightness Typical Value	50,000 Hrs	-	Note

Notes:

- 1. Life time is defined the amount of time when the luminance has decayed to <50% of the initial value.
- 2. This analysis method uses life data obtained under accelerated conditions to extrapolate an estimated probability density function (*pdf*) for the product under normal use conditions.
- 3. Screen saving mode will extend OLED lifetime.



9.Reliability

Content of Reliability Test

Test Item	Content of Test	Test Condition	Applicable Standard
High Temperature storage	Endurance test applying the high storage temperature for a long time.	85°C 240hrs	
_ow Temperature storage	Endurance test applying the low storage temperature for a long time.	-40°C 240hrs	
High Femperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	80°C 240hrs	
_ow Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-40°C 240hrs	
High Femperature/ Humidity Storage	Endurance test applying the high temperature and high humidity storage for a long time.	60°C,90%RH 240hrs	
High Temperature/ Humidity Operation	Endurance test applying the high temperature and high humidity Operation for a long time.	60°C,90%RH 120hrs	
Temperature Cycle	Endurance test applying the low and high temperature cycle. -40°C 25°C 80°C 30min 5min 30min 1 cycle	-40°C /80°C 30 cycles	23
Mechanical Te	st C		
Vibration test	Endurance test applying the vibration during transportation and using.	Frequency:10~55Hz amplitude:1.5mm Time:0.5hrs/axis Test axis:X,Y,Z	
Others	Y 10		
Static electricity test	Endurance test applying the electric stress to the finished product housing.	Air Discharge model ±4kv,10 times	

*** Supply voltage for OLED system =Operating voltage at 25°C



Test and measurement conditions

- 1. All measurements shall not be started until the specimens attain to temperature stability. After the completion of the described reliability test, the samples were left at room temperature for 2 hrs prior to conducting the failure test at 23±5°C; 55±15% RH.
- 2. All-pixels-on is used as operation test pattern.
- 3. The degradation of Polarizer are ignored for High Temperature storage, High Temperature/ Humidity Storage, Temperature Cycle

Evaluation criteria

- 1. The function test is OK.
- 2. No observable defects.
- 3. Luminance: > 50% of initial value.
- 4. Current consumption: within ± 50% of initial value.

APPENDIX:

RESIDUE IMAGE

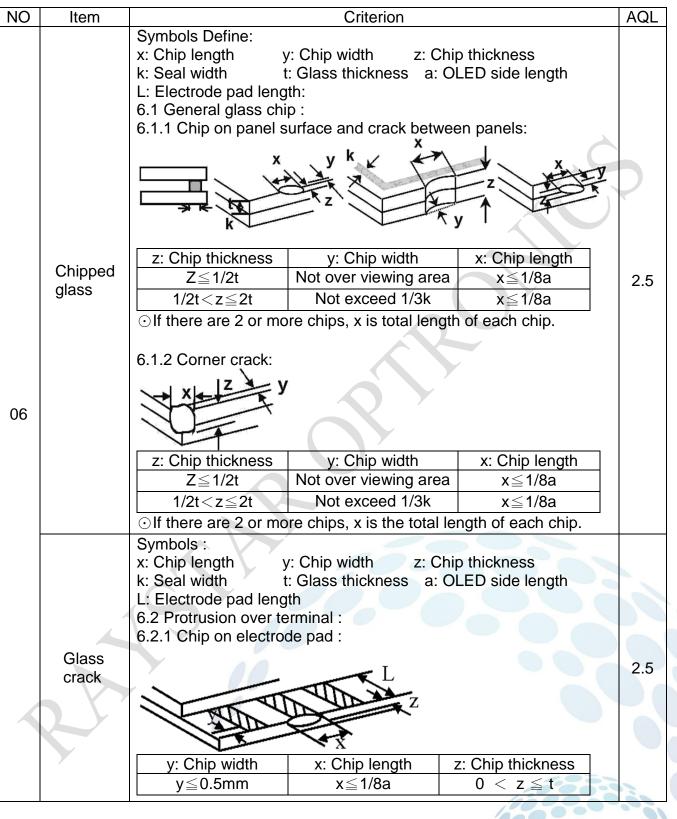
Because the pixels are lighted in different time, the luminance of active pixels may reduce or differ from inactive pixels. Therefore, the residue image will occur. To avoid the residue image, every pixel needs to be lighted up uniformly.



10.Inspection specification

NO	Item			Criterion		AQL		
01	Electrical Testing	 1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 OLED viewing angle defect. 1.7 Mixed product types. 1.8 Contrast defect. 						
02	Black or white spots on OLED (display only)	three white or black	2.1 White and black spots on display ≤ 0.25 mm, no more than three white or black spots present. 2.2 Densely spaced: No more than two spots or lines within 3mm.					
03	OLED black spots, white spots, contamin ation (non-disp lay)	3.1 Round type : As following drawin $\Phi=(x + y) / 2$		SIZE $\Phi \le 0.10$ $0.10 < \Phi \le 0.20$ $0.20 < \Phi \le 0.25$ $0.25 < \Phi$	Acceptable QTY Accept no dense 2 1 0	2.5		
		3.2 Line type : (As f	ollowing c					
		+	Length	Width	Acceptable Q TY			
				W≦0.02	Accept no dense	2.5		
		→i _L •← ,	L≦3.0	$0.02 < W \le 0.03$	2	2.5		
			L≦2.5	$0.03 < W \le 0.05$				
				0.05 <w< td=""><td>As round type</td><td></td></w<>	As round type			
		If bubbles are visibl	e, judge	Size Φ	Acceptable Q TY			
	Polarizer	using black spot specifications, not e	asy to	Φ≦0.20	Accept no dense			
04	bubbles			0.20<Φ≦0.50	3	2.5		
				0.50<Φ≦1.00	2			
	7			1.00<Φ	0			
				Total Q TY	3			
05	Scratches	Follow NO.3 OLED	black spo	ots, white spots, co	ntamination.			
					1.000			







NO	Item	Criterion		
06	Glass crack	6.2.2 Non-conductive portion: y y x x y y x y	AQL 2.5	
07	Cracked glass	The OLED with extensive crack is not acceptable.		
08	Backlight elements	 8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using OLED spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong. 		
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.9.2 Bezel must comply with job specifications.		



NO	Item	Criterion	AQL
	PCB , COB	10.1 COB seal may not have pinholes larger than 0.2mm or contamination.	2.5
		10.2 COB seal surface may not have pinholes through to the IC.10.3 The height of the COB should not exceed the height indicated in the assembly diagram.	2.5 0.65
		10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than	2.5
10		three places. 10.5 No oxidation or contamination PCB terminals.	2.5
		10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts.	0.65
		10.7 The jumper on the PCB should conform to the product characteristic chart.	0.65
		10.8 If solder gets on bezel tab pads, OLED pad, zebra pad or screw hold pad, make sure it is smoothed down.	2.5
	Soldering	11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation	2.5 2.5
11		or icicle. 11.3 No residue or solder balls on PCB.	2.5
		11.4 No short circuits in components on PCB.	0.65
		12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.	2.5
	General appearance	12.2 No cracks on interface pin (OLB) of TCP.	0.65
		12.3 No contamination, solder residue or solder balls on	2.5
12		product.	0.5
		12.4 The IC on the TCP may not be damaged, circuits. 12.5 The uppermost edge of the protective strip on the interface	2.5 2.5
		pin must be present or look as if it cause the interface pin to sever.	2.5
		12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color.	2.5
		12.7 Sealant on top of the ITO circuit has not hardened.	2.5
		12.8 Pin type must match type in specification sheet.	0.65
		12.9 OLED pin loose or missing pins.	0.65
		12.10 Product packaging must the same as specified on	0.65
		packaging specification sheet. 12.11 Product dimension and structure must conform to product	0.65
		specification sheet.	0.00

0



Check Item	Classification	Criteria		
No Display	Major			
Missing Line	Major			
Pixel Short	Major			
Darker Short	Major			
Wrong Display	Major			
Un-uniform /A x 100% < 70% A/C x 100% < 70%	Major	A Normal B Dark Pixel C Light Pixel		

0



11.Precautions in use of OLED Modules

- (1) Avoid applying excessive shocks to module or making any alterations or modifications to it.
- (2) Don't make extra holes on the printed circuit board, change the components or modify its shape of OLED display module.
- (3) Don't disassemble the OLED display module.
- (4) Do not apply input signals while the logic power is off.
- (5) Don't operate it above the absolute maximum rating.
- (6) Don't drop, bend or twist OLED display module.
- (7) Soldering: only to the I/O terminals.
- (8) Hot-Bar FPC soldering condition: 280~350C, less than 5 seconds.
- (9) Raystar has the right to change the passive components (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.) and change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Raystar have the right to modify the version.)
- (10) Raystar has the right to upgrade or modify the product function.

11.1. Handling Precautions

- (1) Since the display panel is being made of glass, do not apply mechanical impacts such as dropping from a high position.
- (2) If the display panel is broken by some accident and the internal organic substance leaks out, be careful not to inhale nor lick the organic substance.
- (3) If pressure is applied to the display surface or its neighborhood of the OLED display module, the cell structure may be damaged. So, be careful not to apply pressure to these sections.
- (4) The polarizer covering the surface of the OLED display module is soft and easily scratched.
- (5) When the surface of the polarizer of the OLED display module has soil, clean the surface. It takes advantage by using following adhesion tape.

* Scotch Mending Tape No. 810 or an equivalent

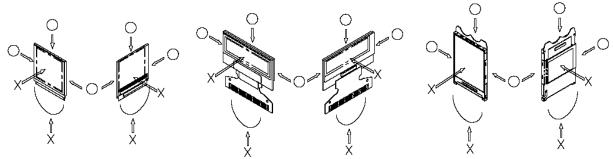
Never try to breathe upon the soiled surface nor wipe the surface using cloth containing solvent such as ethyl alcohol, since the surface of the polarizer will become cloudy.

Also, pay attention that the following liquid and solvent may spoil the polarizer:

- * Water
- * Ketone
- * Aromatic Solvents
- (6) Protection film is being applied to the surface of the display panel and removes the protection film before assembling it. At this time, if the OLED display module has been stored for a long period of time, residue adhesive material of the protection film may remain on the surface of the display panel after removed of the film. In such case, remove the residue material by the method introduced in the above Section 5.
- (7) Do not touch the following sections whenever possible while handling the OLED display modules.
 - * Pins and electrodes
 - * Pattern layouts such as the TCP & FPC
- (8) Hold OLED display module very carefully when placing OLED display module into the



System housing. Do not apply excessive stress or pressure to OLED display module. And, do not over bend the film with electrode pattern layouts. These stresses will influence the display performance. Also, secure sufficient rigidity for the outer cases.



- (9) Do not apply stress to the LSI chips and the surrounding molded sections.
- (10) Pay sufficient attention to the working environments when handing OLED display modules to prevent occurrence of element breakage accidents by static electricity.
 - * Be sure to make human body grounding when handling OLED display modules.
 - * Be sure to ground tools to use or assembly such as soldering irons.

* To suppress generation of static electricity, avoid carrying out assembly work under dry environments.

* Protective film is being applied to the surface of the display panel of the OLED display module. Be careful since static electricity may be generated when exfoliating the protective film.

11.2. Storage Precautions

- (1) When storing OLED display modules, put them in static electricity preventive bags to avoid be directly exposed to sun or lights of fluorescent lamps. (We recommend you to store these modules in the packaged state when they were shipped from Raystar. At that time, be careful not to let water drops adhere to the packages or bags.)
- (2) When the OLED display module is being dewed or when it is placed under high temperature or high humidity environments, the electrodes may be corroded if electric current is applied. Please store it in clean environment.

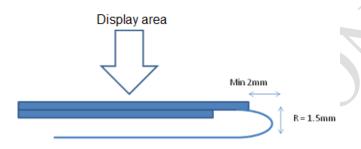
11.3. Designing Precautions

- (1) The absolute maximum ratings are the ratings which cannot be exceeded for OLED display module, and if these values are exceeded, OLED display module may be damaged.
- (2) To prevent occurrence of malfunctioning by noise, pay attention to satisfy the VIL and VIH specification and to make the signal line cable as short as possible.
- (3) We recommend you to install excess current preventive unit (fuses, etc.) to the power circuit (VDD / VCC). (Recommend value: 0.5A)
- (4) Pay sufficient attention to avoid occurrence of mutual noise interference with the nearby devices.
- (5) As for EMI, take necessary measures on the equipment side basically.
- (6) If the power supplied to the OLED display module is forcibly shut down by such errors as taking out the main battery while the OLED display panel is in operation, we cannot guarantee the quality of this OLED display module.

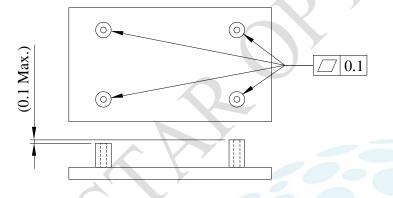
* Connection (contact) to any other potential than the above may lead to rupture of the IC.



- (7) If this OLED driver is exposed to light, malfunctioning may occur and semiconductor elements may change their characteristics.
- (8) The internal status may be changed, if excessive external noise enters into the module. Therefore, it is necessary to take appropriate measures to suppress noise generation or to protect module from influences of noise on the system design.
- (9) We recommend you to make periodical refreshment of the operation statuses (re-setting of the commands and re-transference of the display data) to cope with catastrophic noise.
- (10) It's pretty common to use "Screen Saver" to extend the lifetime and Don't use the same image for long time in real application. When an OLED display module is operated for a long of time with fixed pattern, an afterimage or slight contrast deviation may occur.
- (11) The limitation of FPC and Film bending.



(12) The module should be fixed balanced into the housing, or the module may be twisted.



11.4. Precautions when disposing of the OLED display modules

(1) Request the qualified companies to handle industrial wastes when disposing of the OLED display modules. Or, when burning them, be sure to observe the environmental and hygienic laws and regulations.



		Page: 1					
Modu	Module Sample Estimate Feedback Sheet						
Module Number :							
1 · Panel Specification :							
1. Panel Type :	Pass	□NG ,					
2. Numbers of Pixel :	Pass	□NG ,					
3. View Area :	Pass	□NG ,					
4. Active Area :	Pass	□NG ,					
5.Emitting Color :	Pass	□NG ,					
6.Uniformity:	□Pass	□NG ,					
7.Operating	Pass	□NG ,					
Temperature :		Y Y					
8.Storage Temperature :	Pass	□NG ,					
9.Others :	•						
2 · Mechanical Specificati	on :						
1. PCB Size :	□Pass	□NG ,					
2.Frame Size :	□Pass	□NG ,					
3.Materal of Frame :	□Pass	□NG ,					
4.Connector Position :	□Pass	□NG ,					
5.Fix Hole Position :	□Pass	□NG ,					
6. Thickness of PCB :	□Pass	□NG ,					
7. Height of Frame to	□Pass	□NG ,					
PCB :							
8.Height of Module :	□Pass	□NG ,					
9.Others :	□Pass	□NG ,					
3 · <u>Relative Hole Size</u> :	3 · <u>Relative Hole Size</u> :						
1.Pitch of Connector :	□Pass	□NG ,					
2.Hole size of	□Pass	□NG ,					
Connector :							
3.Mounting Hole size :	□Pass	□NG ,					
4.Mounting Hole Type :	□Pass	□NG ,					
5.Others :	□Pass	□NG ,					

>> Go to page 2 <<



Page: 2

Module Number :						
4 · Electronic Characteristics of Module :						
1.Input Voltage :	□Pass	□NG ,				
2.Supply Current :	□Pass	□NG ,				
3.Driving Voltage for OLED :	□Pass	□NG ,				
4.Contrast for OLED :	□Pass	□NG ,				
5.Negative Voltage Output :	□Pass	□NG ,				
6.Interface Function :	□Pass	□NG ,				
7.ESD test :	□Pass	□NG ,				
8.Others :	□Pass	□NG ,				
E. Summony						

5 \ <u>Summary</u> :

Sales signature : _____ Customer Signature : _____

Date : / /